



Material Composition Sheet

Product: GS4981-CTAE3
Package Type: SOIC-8 taped (2500/reel)
Manufacturer: Gennum Corporation

Date: 16-Jan-2007

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		2.54	Al	0.02	0.78	7874
			Si	2.52	99.21	992126
			Sub-total:	2.54	99.99	1000000
Die Attach	CRM 1076R	0.15	Ag	0.11	73.33	733333
			Epoxy Resin	0.04	26.66	266667
			Sub-total:	0.15	99.99	1000000
Lead Finish External		1.33	Sn	1.33	100.00	1000000
			Sub-total:	1.33	100.00	1000000
Lead Finish Internal		0.19	Ag	0.19	100.00	1000000
			Sub-total:	0.19	100.00	1000000
Leadframe	Olin 194FH	24.26	Cu	23.65	97.48	974856
			Fe	0.57	2.34	23495
			P	0.01	0.04	412
			Zn	0.03	0.12	1237
			Sub-total:	24.26	99.98	1000000
Marking Ink	Wieder W238	0.00		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G600	48.43	Carbon Black	0.15	0.30	3097
			Epoxy Cresol Novolac	1.94	4.00	40058
			Epoxy Resin	2.76	5.69	56989
			Phenol Resin	2.42	4.99	49969
			SiO2	41.17	85.00	850093
			Sub-total:	48.44	99.98	1000206
Wires	SGA3	0.21	Au	0.21	100.00	1000000
			Sub-total:	0.21	100.00	1000000
Total:		77.11				

GENNUM CORPORATION

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